

2N4403
Rev.F Sep.-2016

WR0<5 ¼¼ ¢ SQS æ ¢ ¢ s ¢ ¢ 1

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-40	V
Collector to Emitter Voltage	V_{CEO}	-40	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-600	mA
Collector Power Dissipation	P_C	625	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	200	/W
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C = -0.1mA$ $I_E = 0$	-40			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C = -1.0mA$ $I_B = 0$	-40			V
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E = -0.1mA$ $I_C = 0$	-5.0			V
Collector Cut-Off Current	I_{CBO}	$V_{CB} = -40V$ $I_E = 0$			-50	nA

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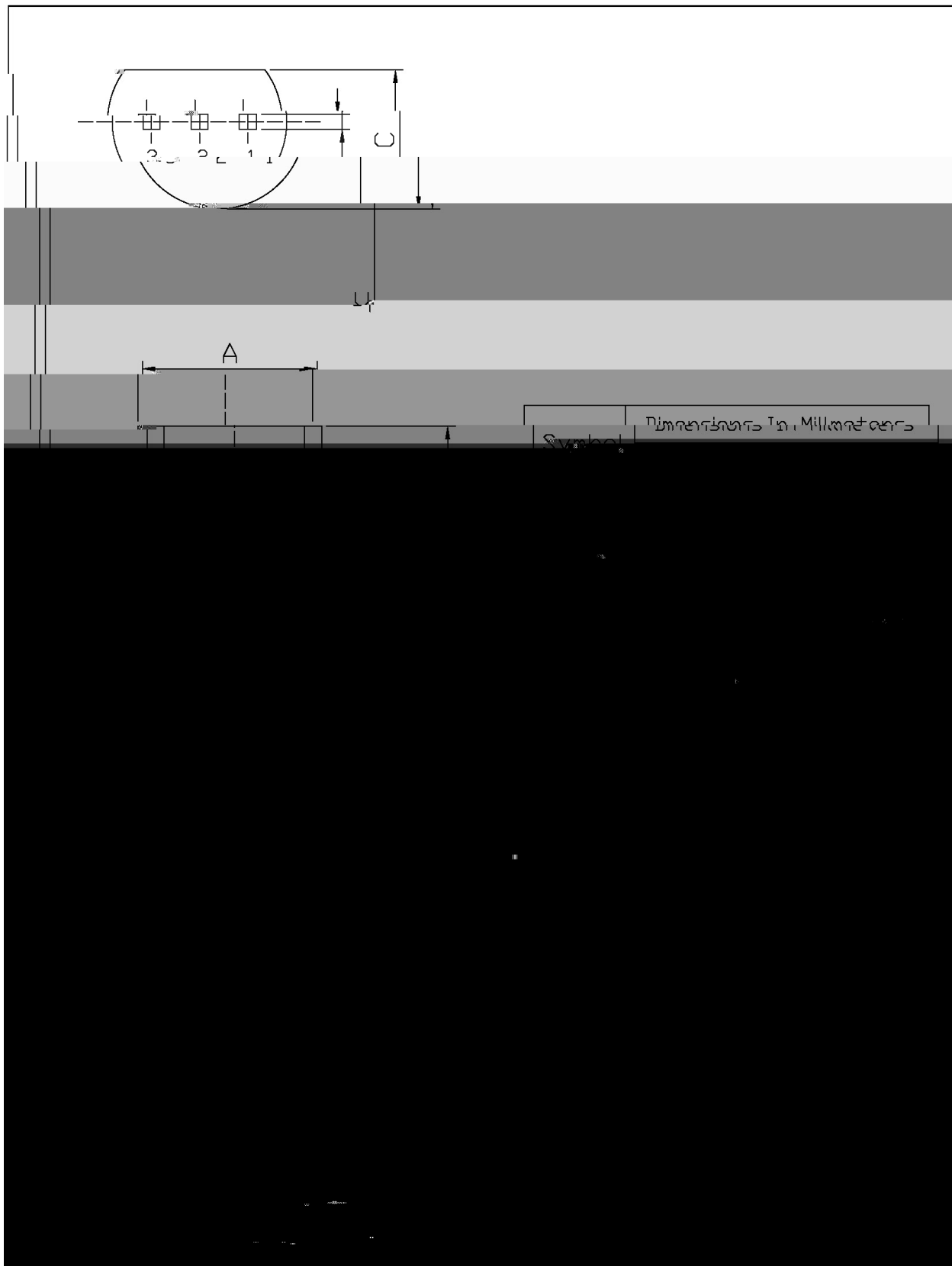
蓝箭电子
BLUE ROCKET ELECTRONICS

DATA SHEET

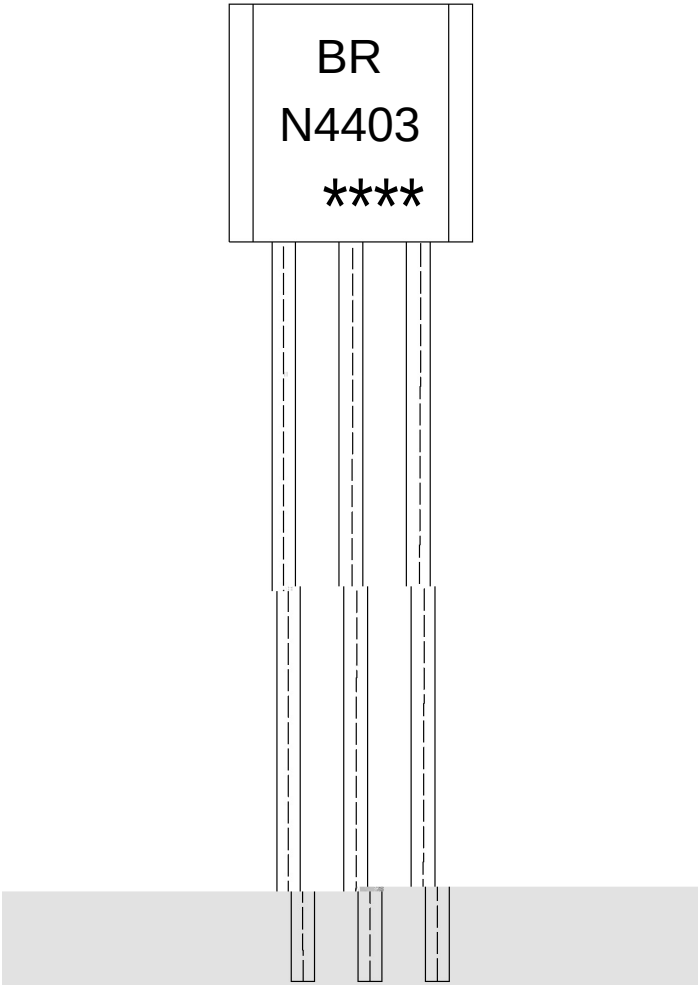
/ Package Dimensions

TO-92

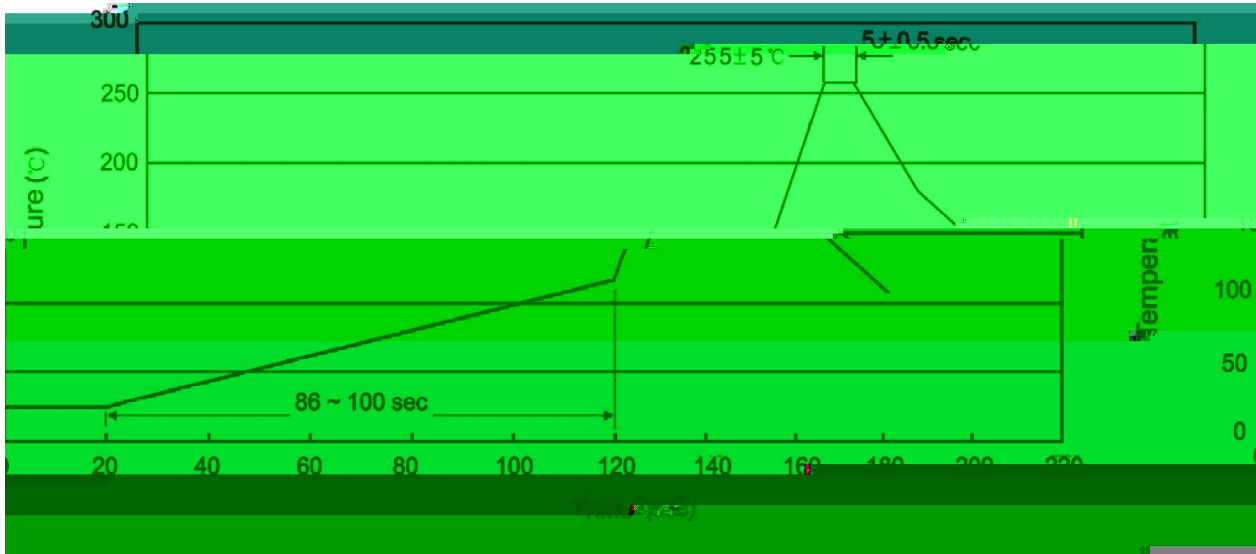
Unit: mm



/ Marking Instructions



公司代码	公司代码
EU	公司代码
Q7736	公司代码
----	公司代码 公司代码 公司代码 公司代码
Note:	
BR:	Company Code.
N4403:	Product Type.
****:	Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)


说明

1. 预加热: 25~150℃, 时间: 60~90sec;
2. 峰值温度: 255±5℃, 持续时间: 5±0.5sec;
3. 冷却速度: 2~10℃/sec.

Note:

1. Preheating: 25~150℃, Time: 60~90sec.
2. Peak Temp.: 255±5℃, Duration: 5±0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

预加热: 270±5℃, 时间: 10±1 sec.

$T_f = 0.56 \text{Db} \cdot 2 \text{f} / \text{TT}^2$ 1 $T_f = 0$ TD=0.0005;